

**3GPP TSG RAN#8**  
**Dusseldorf, Germany, 19 -21 June, 2000**

***RP (00)0315***

**Agenda Item:       6**

**Source:             CWTS**

**To:                 RAN#8**

**Title:              Proposed WI " Low Chip Rate TDD UE Radio Access  
                      Capability "**

**Document for:     Approval**

## Work Item Description

### Title

Low chip rate TDD UE radio access capability

### 1 3GPP Work Area

<b>X</b>	Radio Access
	Core Network
	Services

### 2 Linked work items

*Low Chip Rate TDD physical layer*

*Low chip rate TDD Layer 2 and Layer 3 protocol aspects*

*Low chip rate TDD UTRAN architecture aspects*

*Smart Antenna*

*RF Radio Transmission/Reception, System Performance Requirements and Conformance Testing*

### 3 Justification

The integration of TDD low chip rate option in Release 2000 is discussed and approved in RAN#6. The work plan of the integration of low chip rate TDD in R00 was discussed in RAN#7. As a feature, the low chip rate TDD is sub-divided into several building blocks via the email discussion. For the low chip rate TDD, it has commonalities but also difference on radio access capabilities with the high chip rate TDD option e.g. usage of timeslots for different UE classes, usage of USCH /DSCH, usage of beamforming etc. This paper is to describe one of the low chip rate TDD building block – UE radio access capabilities.

### 4 Objective

The technical objective of this work item is complete the UE radio access capabilities. And this work will affect the specifications for working group on UE radio access capability.

- For UE radio access capability, it includes the following work tasks:
  - Definition of UE radio access capabilities for low chip rate option

Task	Planned Start	Planned Finish
Complete the TR for WG1	01/2000	05/2000
Drafting new specifications and CRs	06/2000	12/2000

### 5 Service Aspects

*None*

### 6 MMI-Aspects

*None*

### 7 Charging Aspects

*None*

### 8 Security Aspects

None

**9 Impacts**

<b>Affects:</b>	<b>USIM</b>	<b>ME</b>	<b>AN</b>	<b>CN</b>	<b>Others</b>
<b>Yes</b>		X	X		
<b>No</b>	X			X	X
<b>Don't know</b>					

**10 Expected Output and Time scale (to be updated at each plenary)**

<b>New specifications</b>						
Spec No.	Title	Prime resp. WG	2ndary resp. WG(s)	Presented for information at plenary#	Approved at plenary#	Comments
<b>Affected existing specifications</b>						
Spec No.	CR	Subject			Approved at plenary#	Comments
25.926		UE Radio Access Capabilities			RAN #10	

**11 Work item rapporteurs**

Mr. Yanhui LIU (CATT/CWTS)

**12 Work item leadership**

RAN WG2

**13 Supporting Companies**

Ericsson, Fujitsu, IDC, LG, NTT DoCoMo, Panasonic, RFI, Samsung, Siemens

**14 Classification of the WI (if known)**

	Feature (go to 14a)
X	Building Block (go to 14b)
	Work Task (go to 14c)

14a The WI is a Feature: List of building blocks under this feature

(list of Work Items identified as building blocks)

14b The WI is a Building Block: parent Feature

Low chip rate TDD

14c The WI is a Work Task: parent Building Block

(one Work Item identified as a building block)